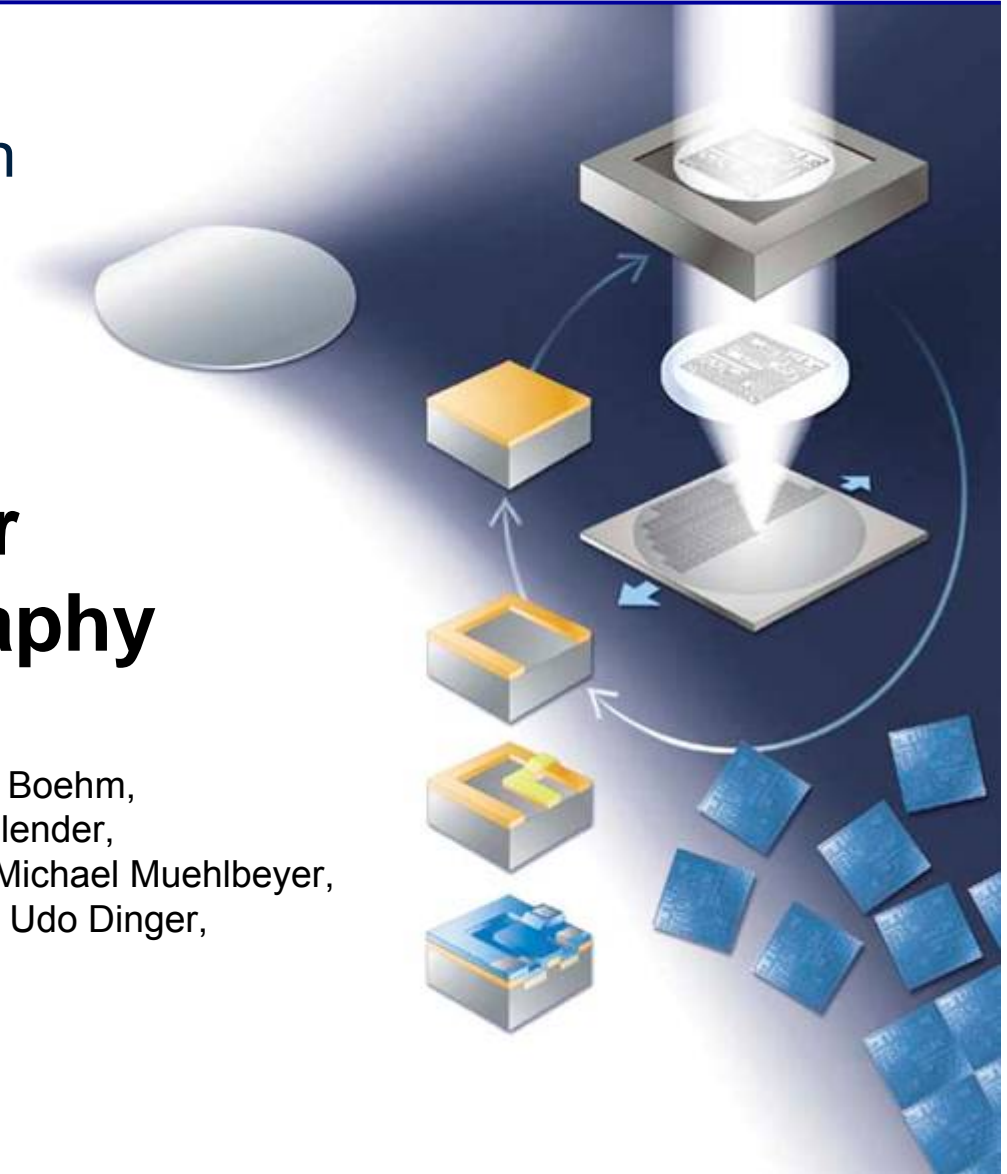


Lithography Optics Division

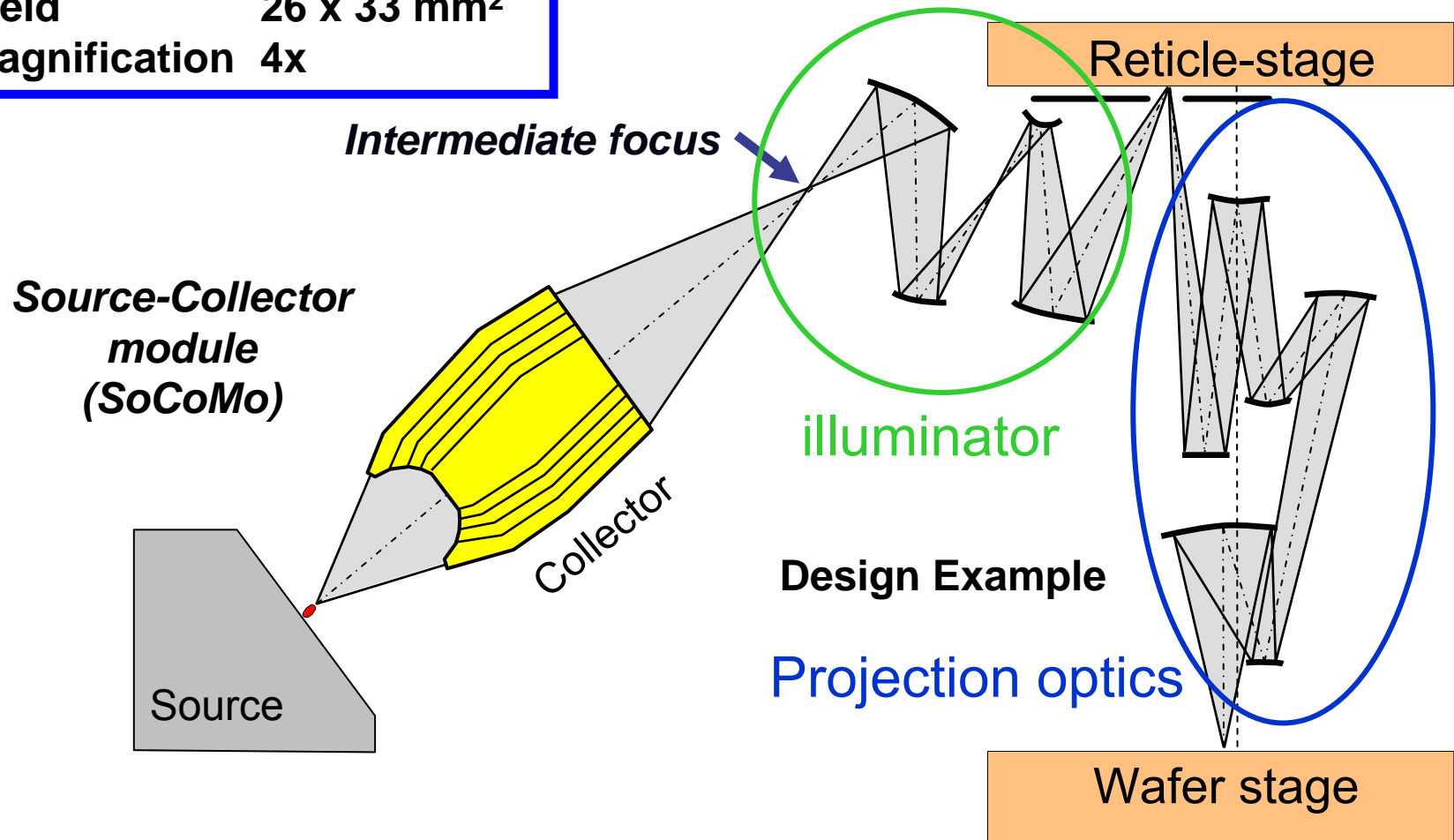
Optics for EUV Lithography

Martin Lowisch, Peter Kuerz, Thure Boehm,
Hans-Juergen Mann, Stephan Muellender,
Wolfgang Bollinger, Manfred Dahl, Michael Muehlbeyer,
Siegfried Rennon, Frank Rohmund, Udo Dinger,
Thomas Stein, and Winfried Kaiser

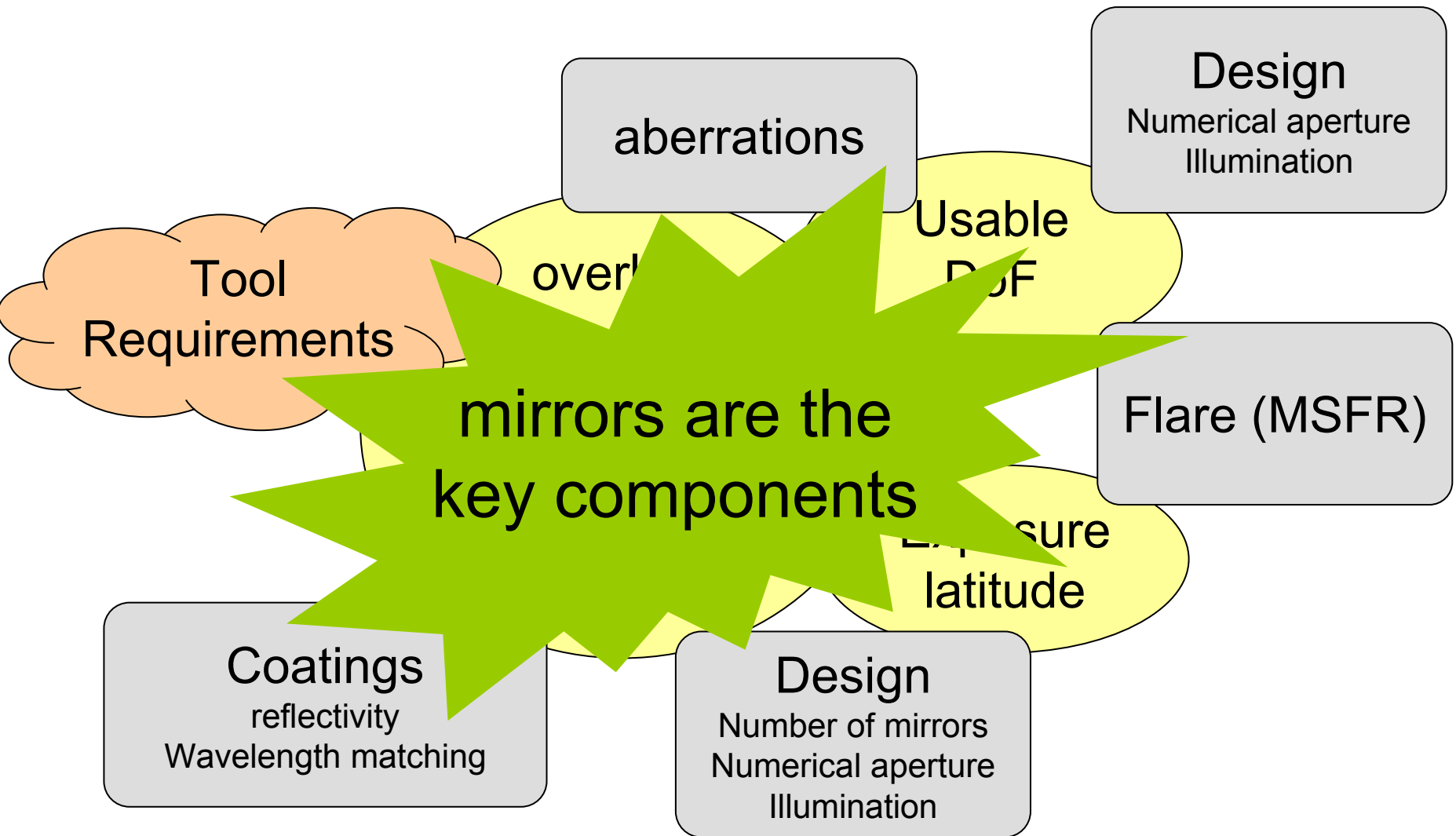


The optical train – Introduction

- λ 13.5 nm
- NA 0.25
- Field 26 x 33 mm²
- Magnification 4x

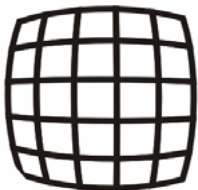
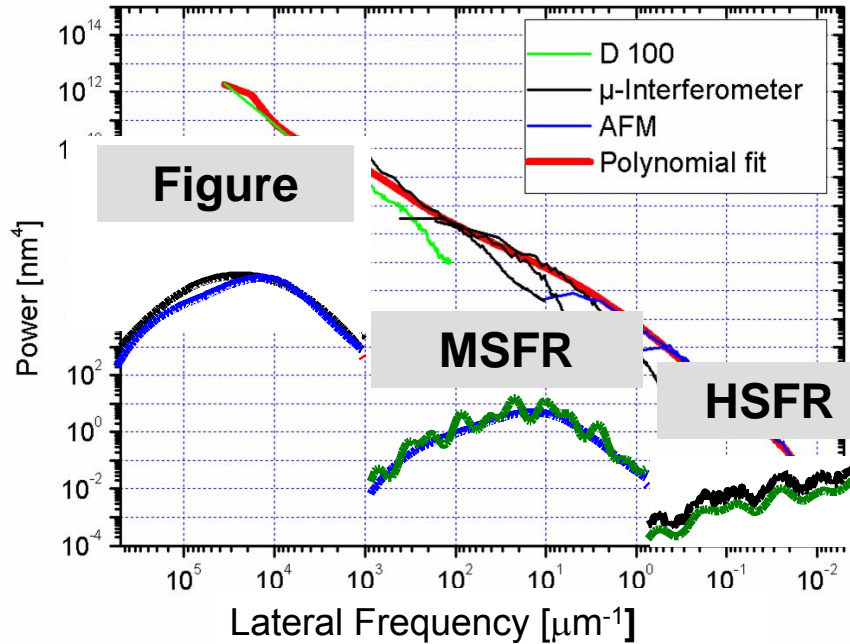


Impact of optics on tool performance



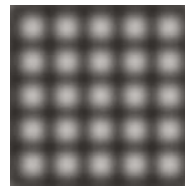
Optics Technology: Fabrication of EUV mirrors

2D-isotropic PSD
(example)



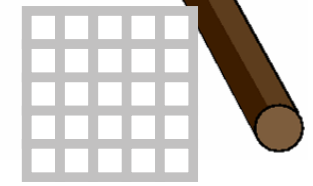
figure

- aberrations
- **CDU, overlay**



MSFR

- in field of view scattering: flare
- **CDU**



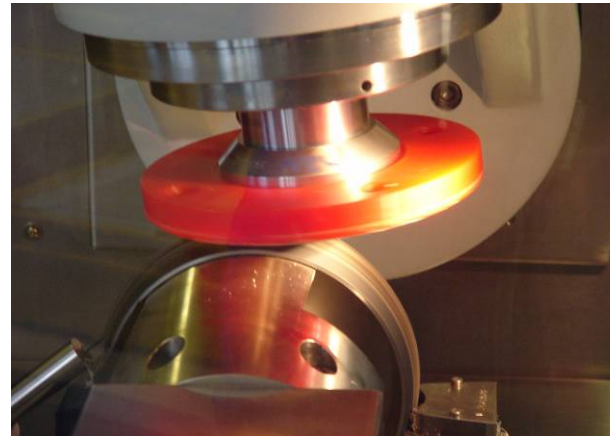
HSFR

- reduced reflectivity
- **system throughput**

The “right” combination of fabrication technologies...



Computer Controlled Polishing for Deterministic Processes



Fast Magneto Rheological Figuring



**Ion Beam Figuring:
Atomic Level Figure Control**

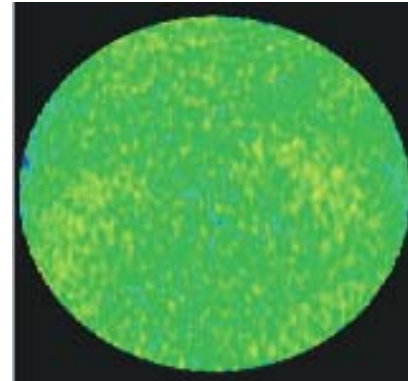
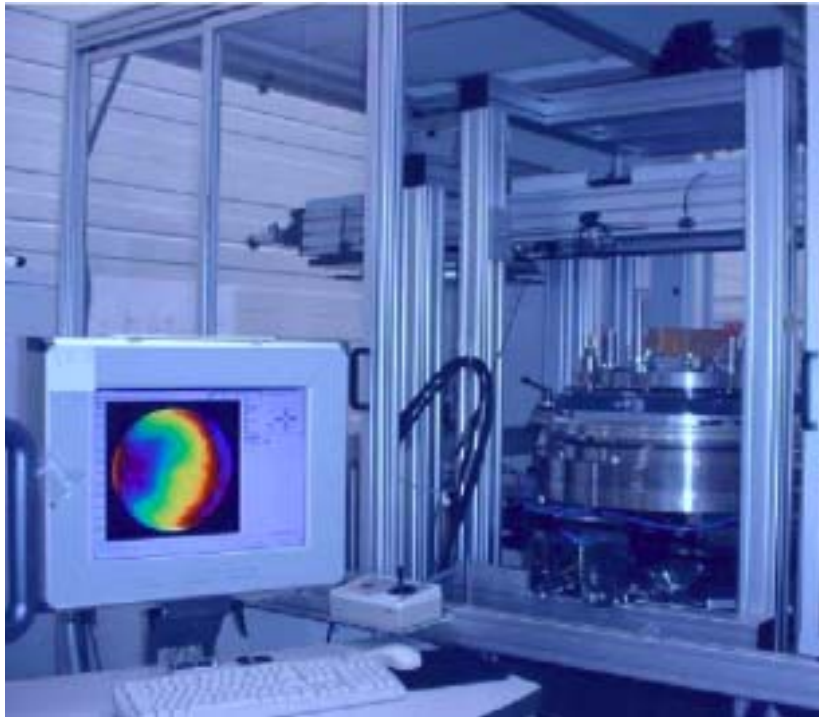
•The challenge for optics fabrication:

Reduction of the Mid Spatial Frequency Roughness MSFR

... and at the same time reduction of the figure (→ aberration control) and the HSFR (mirror reflectivity → system transmission)

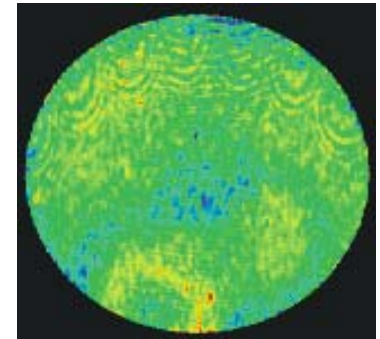
... and improvements in mirror metrology

... enable very low figure values and reduced long wavelength MSFR contributions



← **12 pm RMS
Repeatability**

**20 pm RMS
Reproducibility** →



- statistical errors (repeatability):
 $E_S = 12 \text{ pm RMS surface figure !!!}$
- statistical errors + adjustment errors (reproducibility):
 $E_J = 20 \text{ pm RMS surface figure !!!}$

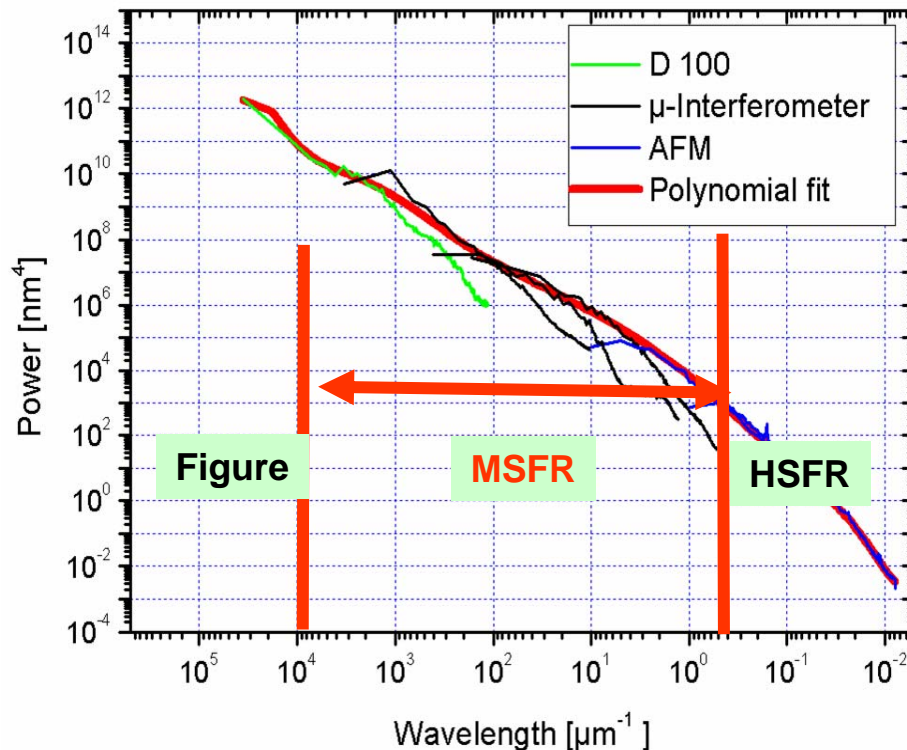
New result on EUV mirror
 Figure = 0.04 nm rms
 MSFR = 0.13 nm rms
 HSMR = 0.07 nm rms

Optics Fabrication:

Flare is determined by the Mid Spatial Frequency roughness

- Due to the small wavelength EUV is extremely sensitive to flare

$$Flare \propto n_{mirrors} \cdot (MSFR/\lambda)^2$$

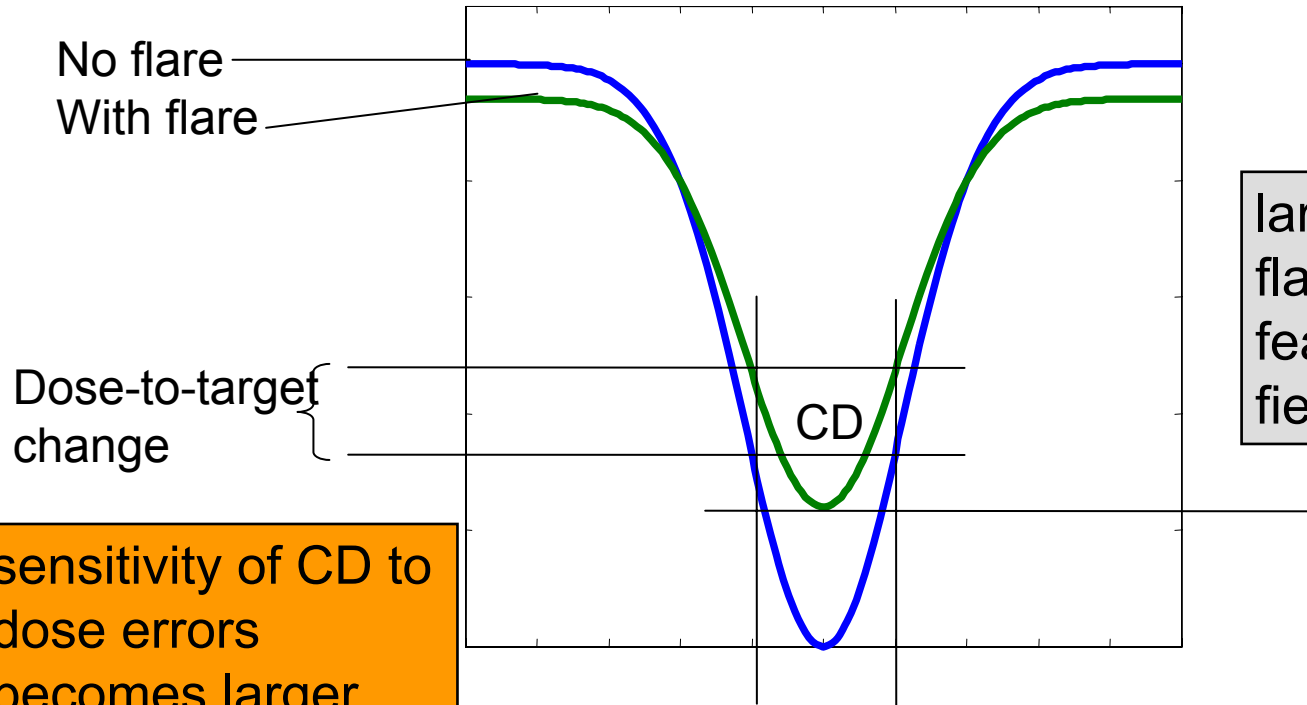


Power spectral density (example)

Definition: All wavelengths of the Power Spectral Density which generate in-field scattering contribute to the MSFR

Main challenge: flare reduction

Intensity cross-section



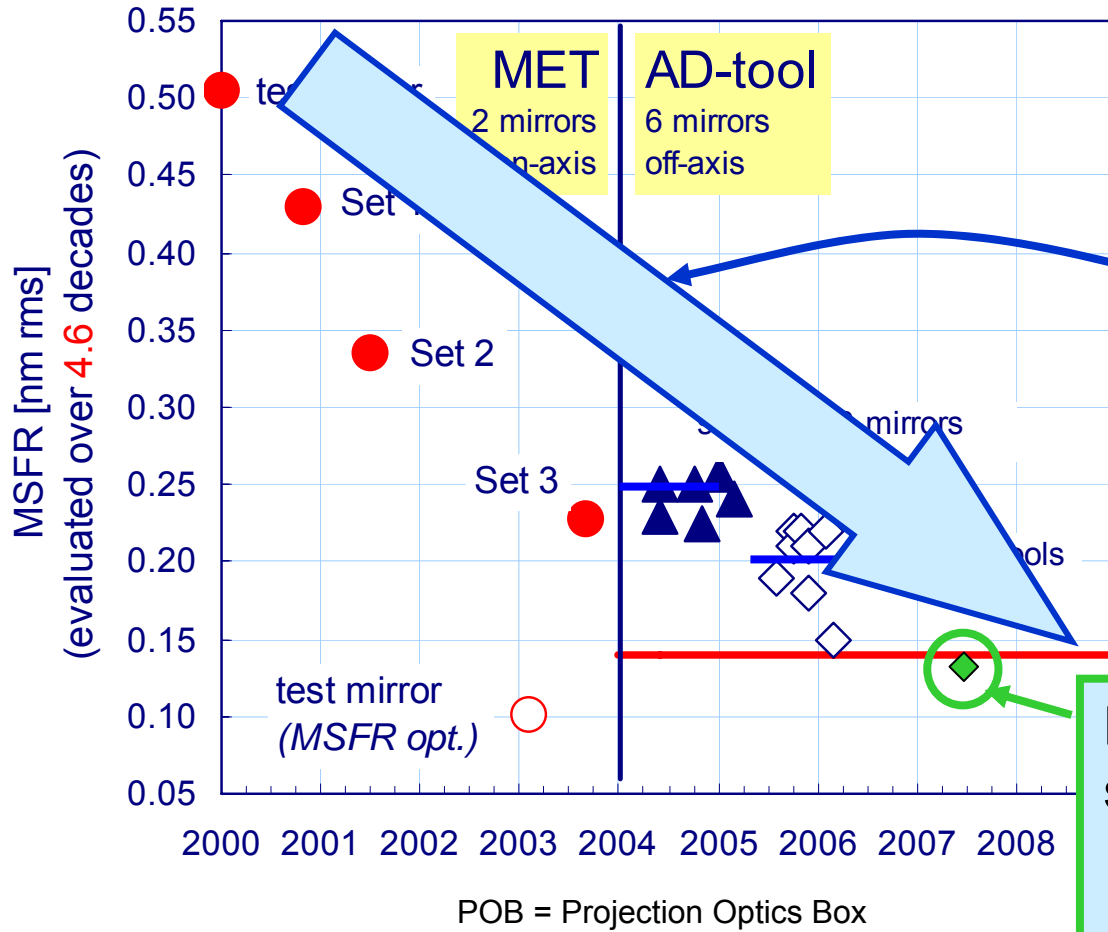
sensitivity of CD to dose errors becomes larger

proximity effects in dependence of the local reticle transmission

flare reduces overlap of process windows due to dose offsets

Progress in flare reduction

Flare is calculated for a 2 μm line in a bright field



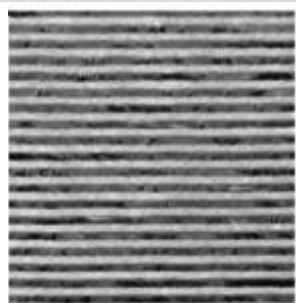
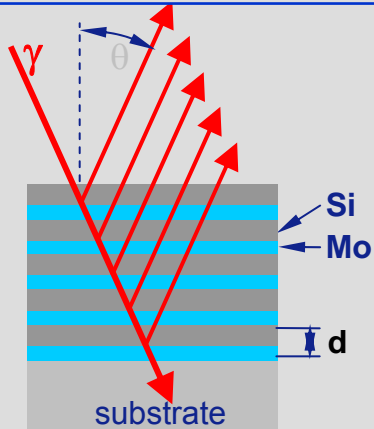
$$Flare \propto n_{mirrors} \cdot (MSFR/\lambda)^2$$

Development focuses on material, polishing, and figuring

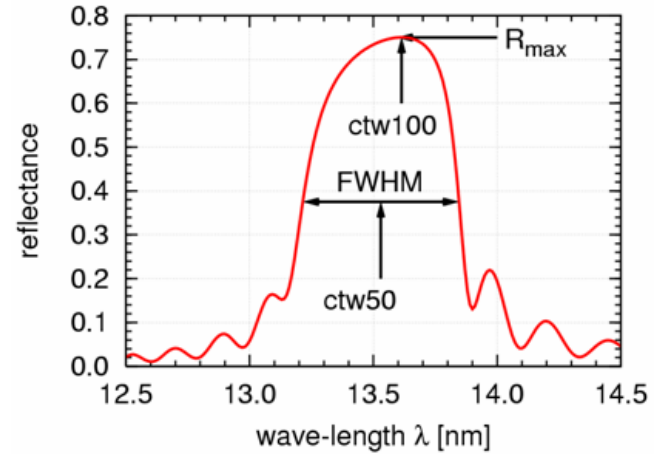
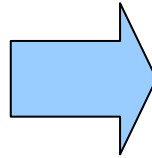
New result on EUV mirror supports flare level < 8%
 Figure = 0.04 nm rms
 MSFR = 0.13 nm rms
 (0.06 nm rms in 3 decades)
 HSFR = 0.07 nm rms

Coating Technology: EUV requires (almost) perfect nanolayers...

EUV coatings:
Mo/Si
Bragg reflectors



> 50 bilayers

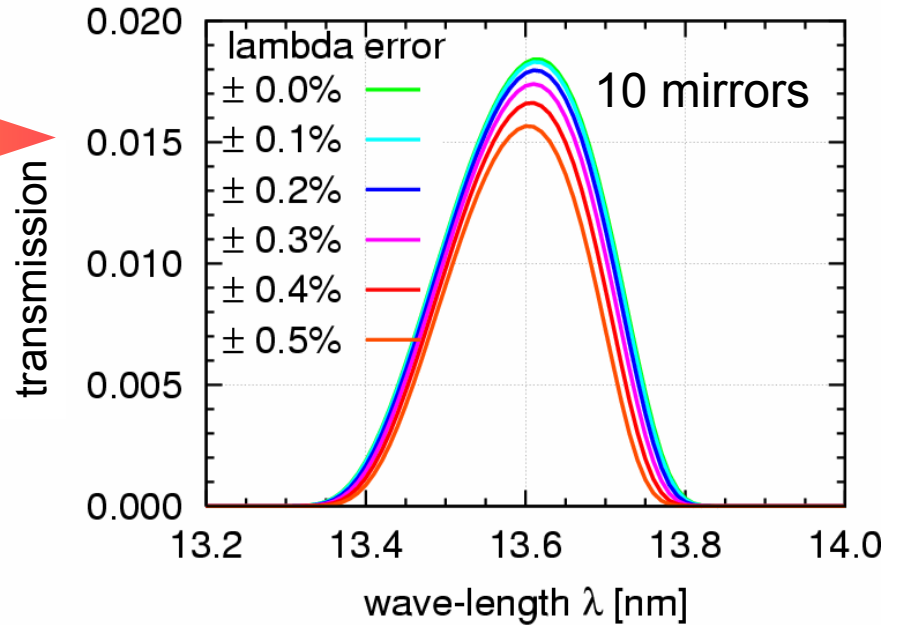
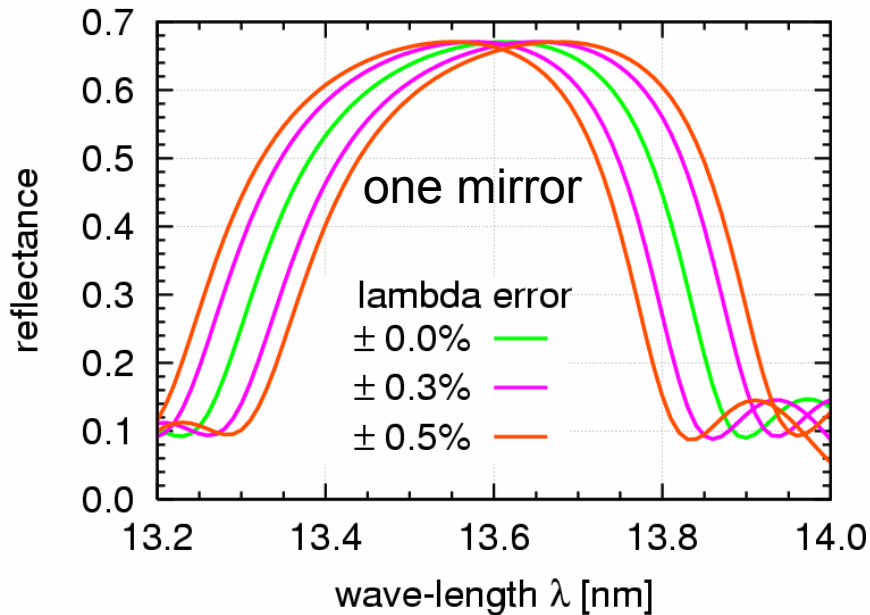


Challenges

high peak reflectance and large FWHM	wave-length matching
> 70% shown	< 0.2% shown

Wave-length matching: transmission of a 10-mirror system

Impact on a generic 10-mirror system



matching	Transmission (integral)
± 0.0%	1.00
± 0.1%	0.99
± 0.2%	0.95
± 0.3%	0.90
± 0.4%	0.83
± 0.5%	0.75

EUV Optics: The future

EUV is introduced as a high k1 technology

Node ≠ NA	0.25	0.35	0.5
32 nm	0.59		1.19
22 nm	0.41	0.57	
16 nm	0.30	0.41	0.59
11 nm	0.20	0.29	0.41

k1 reduction

constant k1

$$RES = k_1 \frac{\lambda}{NA}$$

opportunity

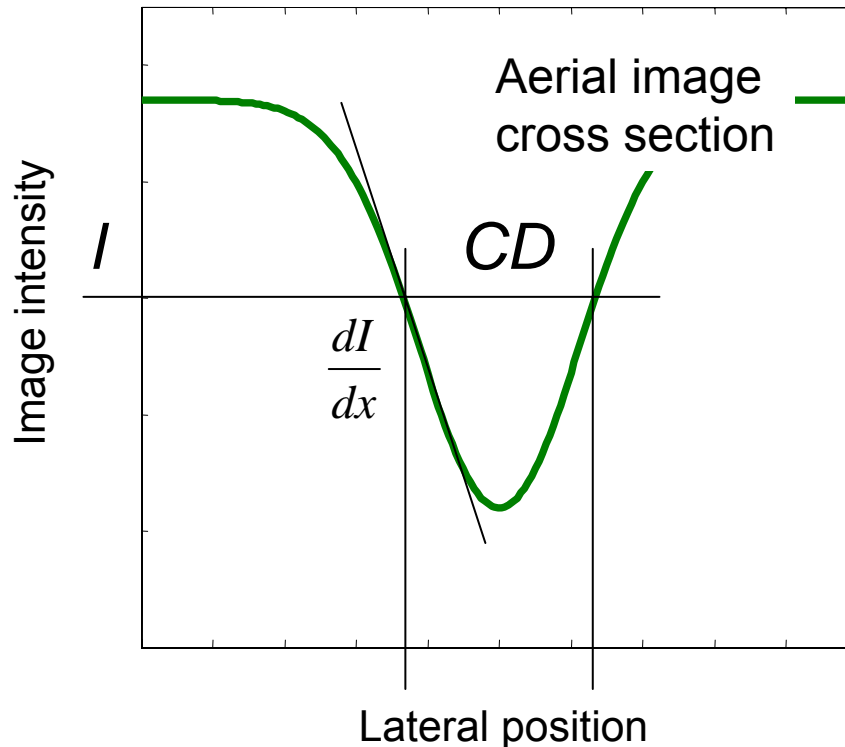
The next step:

0.25 NA projection optics with sigma > 0.7 illumination systems (with oblique illumination) enables:

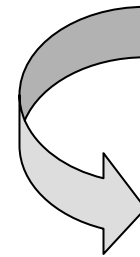
- 32 nm half pitch production
- 22 nm half pitch R+D

Image log-slope is key parameter

How much contrast (image slope) do we have?



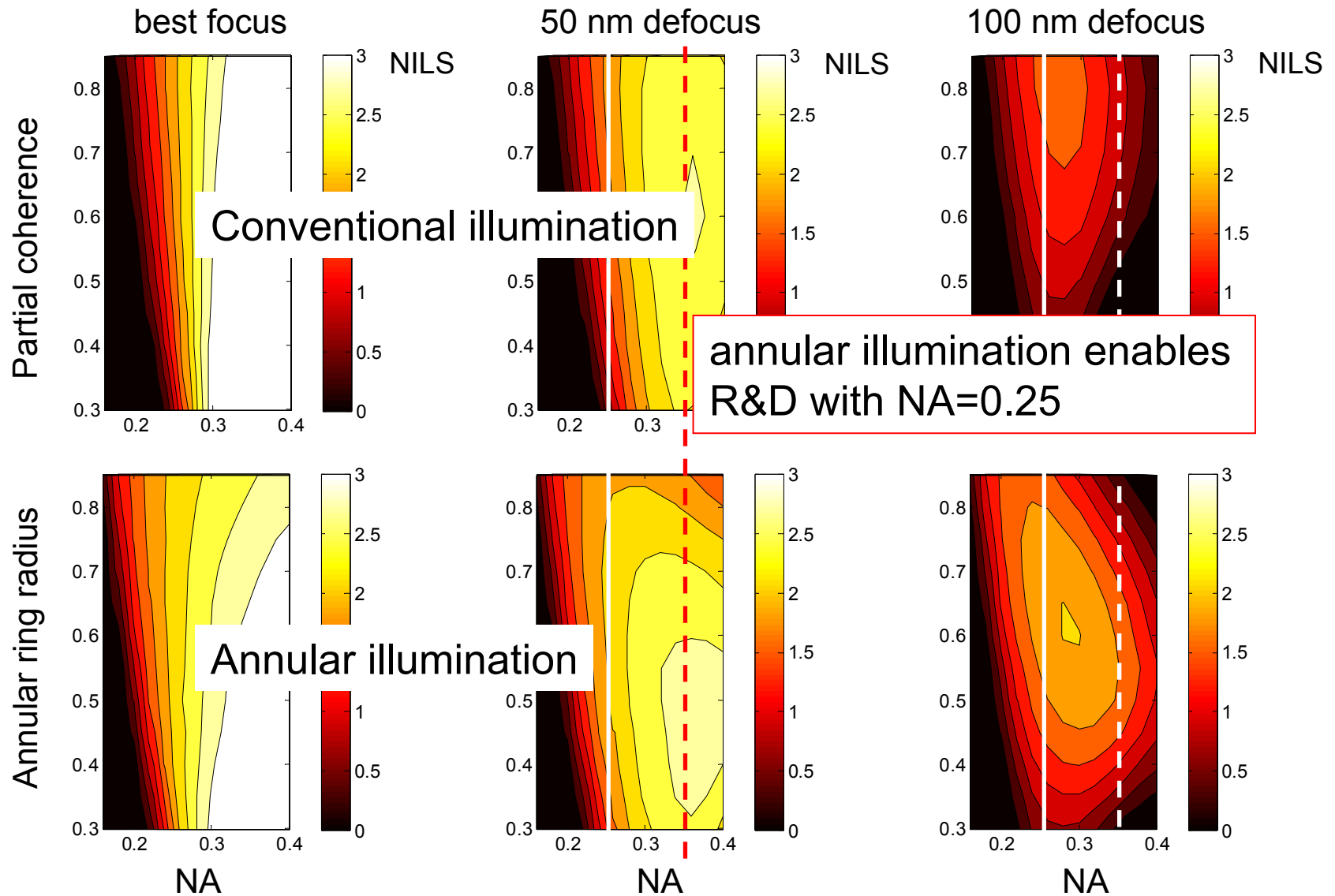
$$NILS = \frac{1}{I} \frac{dI}{dx} CD$$



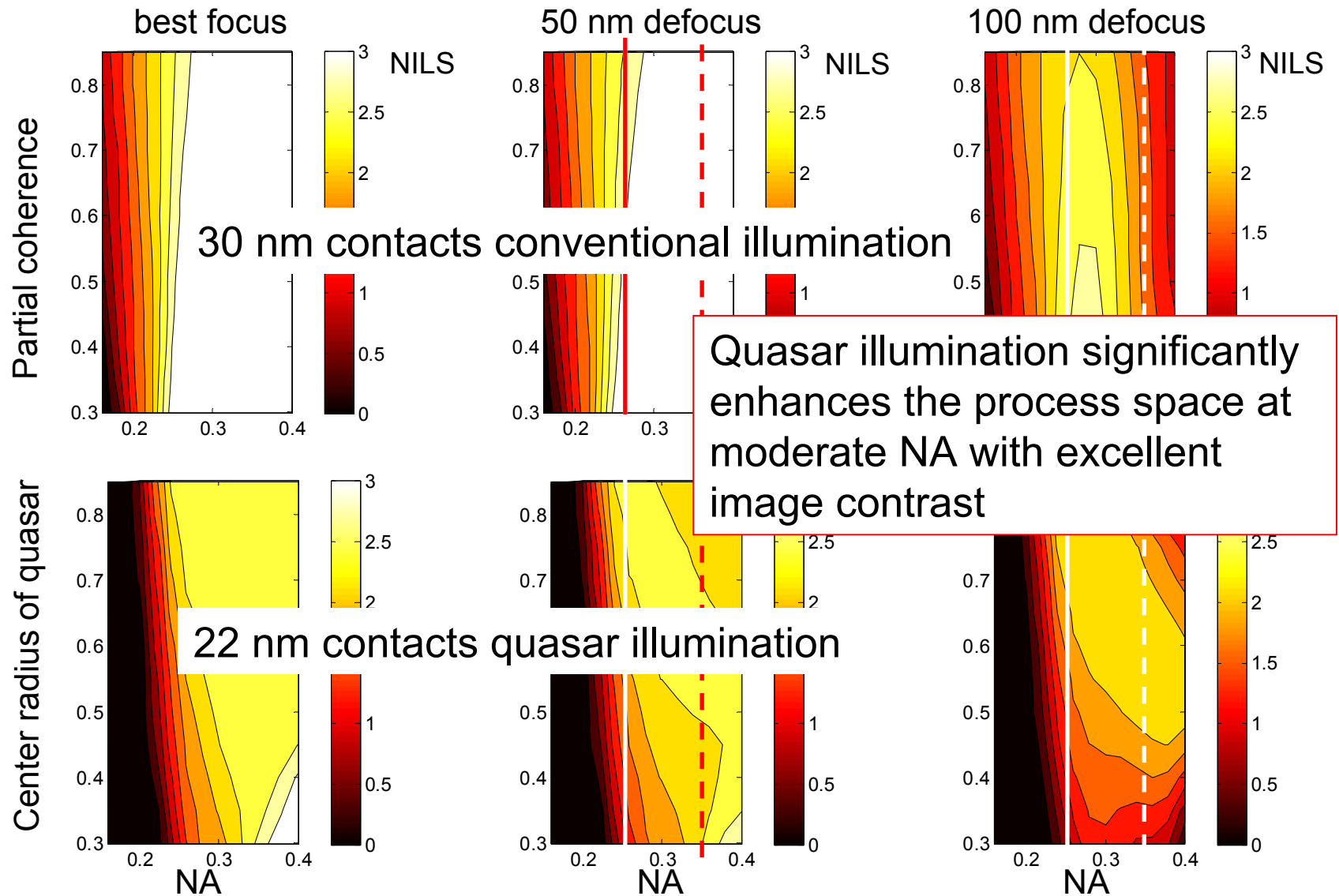
$$\frac{\Delta E}{E} = \frac{NILS}{2} \frac{\Delta CD}{CD}$$

NILS is proportional to exposure latitude

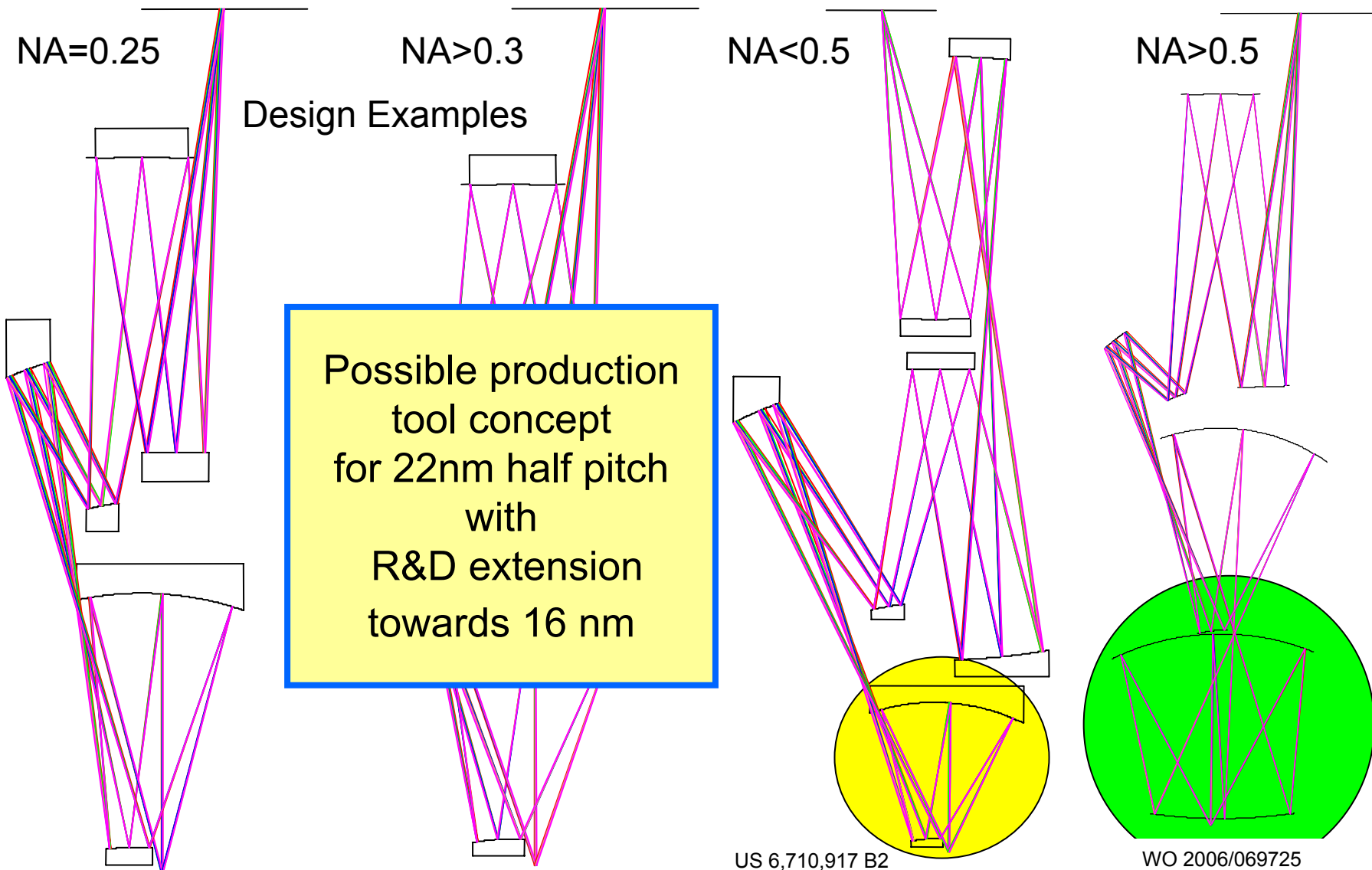
Dense lines 22 nm with conventional and annular illumination



dense contacts with conventional and quasar illumination



And another step: Extendibility of EUV – design concepts



Summary

- key technologies are progressing towards production tool requirements
 - mirror figure
 - flare
 - coating technology (reflectivity, wavelength matching)
- Improved NA = 0.25 systems will address
 - 32 nm half pitch (production)
 - 22 nm half pitch (R+D)
- optical designs with NA > 0.3 support 22 nm half pitch production
- with designs for even higher NA's (≥ 0.5) resolutions down to 16 nm and beyond arise at the horizon

Acknowledgment

Thanks to a huge team effort at...

- FOM-Rijnhuizen
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- Philips
- Heidenhain
- The teams at ASML and Zeiss
- ...and many others

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